

# STGW50NC60W

## N-channel 600V - 55A - TO-247 Ultra fast switching PowerMESH™ IGBT

### Features

Туре	V <sub>CES</sub>	V <sub>CE(sat)</sub> (max)@25°C	Ι <sub>C</sub> @100°C
STGW50NC60W	600V	< 2.6V	55A

- Very high frequency operation
- Low C<sub>RES</sub> / C<sub>IES</sub> ratio (no cross-conduction susceptibility)

## Applications

- Very high frequency inverters, UPS
- HF, SMPS and PFC in both hard switch and resonant topologies
- Motor drivers
- Welding

## Description

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH<sup>™</sup> IGBTs, with outstanding performances. The suffix "W" identifies a family optimized for very high frequency applications.



Table 1.	<b>Device summary</b>
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Order code	Marking	Package	Packaging
STGW50NC60W	GW50NC60W	TO-247	Tube

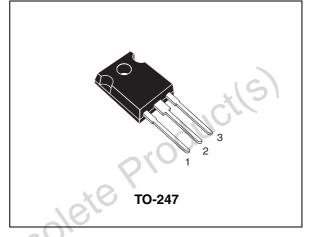
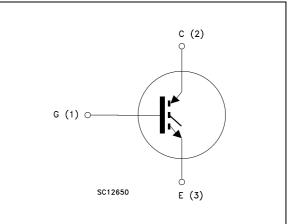


Figure 1. Internal schematic diagram



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### **Electrical ratings** 1

Table 1.	Absolute	maximum	ratings
	Absolute	maximum	raungo

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-emitter voltage ( $V_{GS} = 0$ )	600	V
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at $T_C = 25^{\circ}C$	100	А
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at $T_C = 100^{\circ}C$	55	А
I <sub>CL</sub> <sup>(2)</sup>	Turn-off SOA minimum current	250	А
$V_{GE}$	Gate-emitter voltage	±20	V
P <sub>TOT</sub>	Total dissipation at $T_{C} = 25^{\circ}C$	285	W
Тj	Operating junction temperature	-55 to 150	°C
1. Calculate	d according to the iterative formula:	R	
	$I_{C}(T_{C}) = \frac{T_{JMAX} - T_{C}}{R_{THJ-C} \times V_{CESAT(MAX)}(T_{C})}$	<sup>I</sup> C)	
2. V <sub>clamp</sub> = -	480V, T <sub>J</sub> =150°C, R <sub>G</sub> =10Ω, V <sub>GE</sub> =15V		
Table 2.	Thermal resistance		
			<del></del>

$$I_{C}(T_{C}) = \frac{T_{JMAX} - T_{C}}{R_{THJ-C} \times V_{CESAT(MAX)}(T_{C}, I_{C})}$$

#### Table 2. Thermal resistance

	Symbol	Parameter	Value	Unit
	Rthj-case	Thermal resistance junction-case max IGBT	0.45	°C/W
	Rthj-amb	Thermal resistance junction-ambient max	50	°C/W
Obsole	tePr	00		

### **Electrical characteristics** 2

(T<sub>CASE</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>BR(CES)</sub>	Collector-emitter breakdown voltage	I <sub>C</sub> = 1mA, V <sub>GE</sub> = 0	600			v
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 40A V <sub>GE</sub> = 15V, I <sub>C</sub> =40A,Tc=125°C		2.1 1.9	2.6	v v
V <sub>GE(th)</sub>	Gate threshold voltage	$V_{CE} = V_{GE}$ , $I_C = 250 \mu A$	3.75		5.75	v
I <sub>CES</sub>	Collector cut-off current (V <sub>GE</sub> = 0)	V <sub>CE</sub> = Max rating,T <sub>C</sub> = 25°C V <sub>CE</sub> = Max rating,T <sub>C</sub> = 125°C		30	500 5	μA mA
I <sub>GES</sub>	Gate-emitter leakage current (V <sub>CE</sub> = 0)	$V_{GE}$ = ±20V, $V_{CE}$ = 0	0		±100	nA
9 <sub>fs</sub>	Forward transconductance	V <sub>CE</sub> = 15V <sub>,</sub> I <sub>C</sub> =40A		25		S
	_	5010				
Table 4.	Dynamic	$\sim$				
Symbol	Parameter	Test conditions	Min	Tvn	Max	Unit

#### Table 4. Dynamic

	Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
	C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>CE</sub> = 25V, f = 1MHz, V <sub>GE</sub> = 0		4700 410 90		pF pF pF
	Q <sub>g</sub> Q <sub>ge</sub> Q <sub>gc</sub>	Total gate charge Gate-emitter charge Gate-collector charge	$V_{CE}$ = 390V, I <sub>C</sub> = 40A, $V_{GE}$ = 15V, <i>Figure 16</i>		195 32 82		nC nC nC
obsole		<u>.</u>					

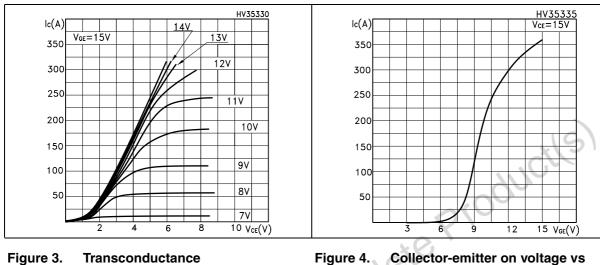
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 390V, I_{C} = 40A$ $R_{G} = 10\Omega, V_{GE} = 15V$		52 17 2400		ns ns A/µs
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 390$ V, $I_C = 40$ A $R_G = 10\Omega$ , $V_{GE} = 15$ V, Tj = 125°C		50 19 2020		ns ns A/µs
t <sub>r(Voff)</sub> t <sub>d(Voff)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 390V, I_{C} = 40A$ $R_{G} = 10\Omega, V_{GE} = 15V,$		31 240 35	19	ns ns ns
t <sub>r(Voff)</sub> t <sub>d(Voff)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 390V, I_C = 40A$ $R_G = 10\Omega, V_{GE} = 15V,$ $Tj = 125^{\circ}C$	,00	59 280 63		ns ns ns

Table 5. Switching on/off (inductive load)

Table 6.

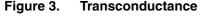
Table 6. Switching energy (inductive load)SymbolParameterTest conditionsMin.Typ.Max.Unit $E_{on}$ Turn-on switching losses $V_{CC} = 390V$ , $I_C = 40A$ $365$ $470$ $\mu J$ $E_{off}^{(1)}$ Turn-off switching losses $V_{CC} = 390V$ , $I_C = 40A$ $365$ $470$ $\mu J$ $E_{ts}$ Total switching losses $Figure 15$ $925$ $1260$ $\mu J$ $E_{on}$ Turn-on switching losses $V_{CC} = 390V$ , $I_C = 40A$ $635$ $\mu J$ $E_{on}$ Turn-on switching losses $V_{CC} = 390V$ , $I_C = 40A$ $635$ $\mu J$
Eon Eoff(1)Turn-on switching losses Turn-off switching losses $V_{CC} = 390V, I_C = 40A$ $R_G = 10\Omega, V_{GE} = 15V,$ Figure 15 $365$ $560$ $925$ $470$ $\mu J$ $\mu J$ E t F Total switching losses $V_{CC} = 390V, I_C = 40A$ $Figure 15$ $365$ $1260$ $470$ $\mu J$
$\begin{array}{c c} E_{off}^{(1)} \\ E_{ts} \end{array} \begin{array}{c} \text{Turn-off switching losses} \\ \text{Total switching losses} \end{array} \end{array} \begin{array}{c} R_{G} = 10\Omega, V_{GE} = 15V, \\ Figure 15 \end{array} \begin{array}{c} 560 \\ 925 \end{array} \begin{array}{c} 790 \\ 1260 \end{array} \begin{array}{c} \mu J \\ \mu J \end{array}$
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$

### **Electrical characteristics (curves)** 2.1

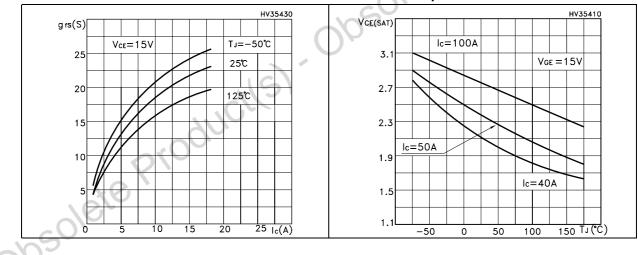


#### Figure 1. **Output characteristics**

Figure 2. **Transfer characteristics** 



Collector-emitter on voltage vs temperature



57

VGE (th)

(norm)

1.

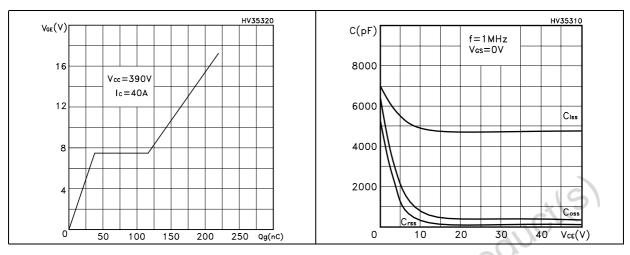
1.0

0.9

0.8

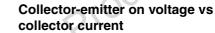
0.7

57



#### Figure 5. Gate charge vs gate-source voltage Figure 6. **Capacitance variations**

Figure 7. Normalized gate threshold voltage Figure 8. vs temperature



HV35390

-50°C

25°C

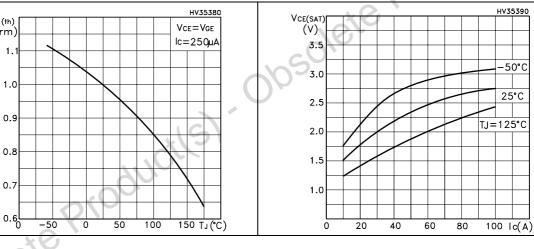


Figure 9. Normalized breakdown voltage vs temperature

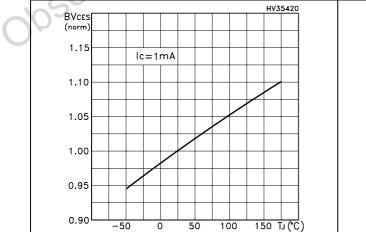
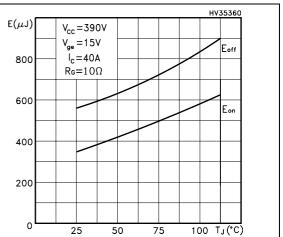


Figure 10. Switching losses vs temperature



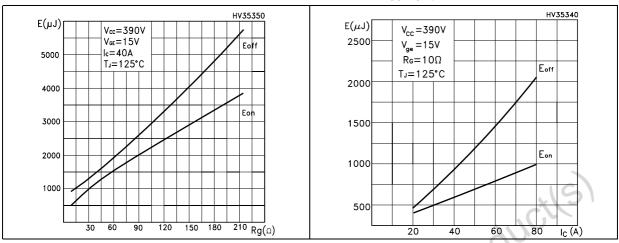


Figure 11. Switching losses vs gate resistance Figure 12. Switching losses vs collector current

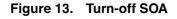
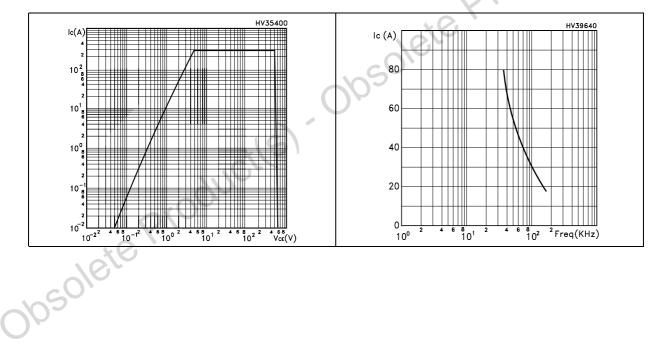


Figure 14. I<sub>C</sub> vs. frequency





oductls

### 2.2 Frequency applications

For a fast IGBT suitable for high frequency applications, the typical collector current vs. maximum operating frequency curve is reported. That frequency is defined as follows:

 $f_{MAX} = (P_D - P_C) / (E_{ON} + E_{OFF})$ 

• The maximum power dissipation is limited by maximum junction to case thermal resistance:

### Equation 1

 $P_D = \Delta T / R_{THJ-C}$ 

considering  $\Delta T = T_J - T_C = 125 \text{ °C} - 75 \text{ °C} = 50 \text{ °C}$ 

The conduction losses are:

### **Equation 2**

 $\mathsf{P}_{\mathsf{C}} = \mathsf{I}_{\mathsf{C}} * \mathsf{V}_{\mathsf{CE}(\mathsf{SAT})} * \delta$ 

with 50% of duty cycle,  $V_{CESAT}$  typical value @125°C.

• Power dissipation during ON & OFF commutations is due to the switching frequency:

### **Equation 3**

 $P_{SW} = (E_{ON} + E_{OFF}) * freq.$ 

Typical values @ 125°C for switching losses are used (test conditions: V<sub>CE</sub> = 390V, V<sub>GE</sub> = 15V, R<sub>G</sub> = 10 Ohm). Furthermore, diode recovery energy is included in the E<sub>ON</sub> (see note 2), while the tail of the collector current is included in the E<sub>OFF</sub> measurements (see note 3).

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## 3 Test circuit

Figure 15. Test circuit for inductive load

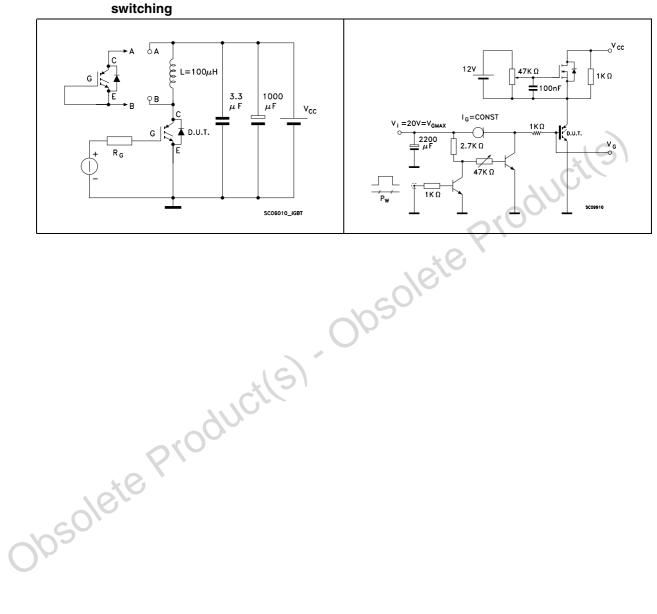


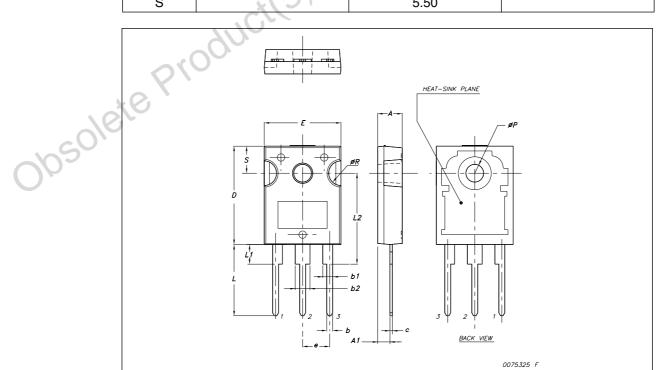
Figure 16. Gate charge test circuit

## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: *www.st.com* 

obsolete Product(s). Obsolete Product(s)

Dim.	mm.			
	Min.	Тур	Max.	
A	4.85		5.15	
A1	2.20	2.60		
b	1.0 1.40		1.40	
b1	2.0 2.4		2.40	
b2	3.0		3.40	
с	0.40		0.80	
D	19.85		20.15	
E	15.45	<b>X</b>	15.75	
е		5.45		
L	14.20		14.80	
L1	3.70		4.30	
L2	(	18.50		
øP	3.55	D.	3.65	
øR	4.50		5.50	



## 5 Revision history

Table 7.Document revision history

Date	Revision	Changes
24-Aug-2007	1	Initial release.

obsolete Product(s). Obsolete Product(s)

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